7. Package Related Reliability Test Data

Temperature Cycle Test (TCT)

1. Test Condition

Condition: T = -65°C / 15min , +150 °C/15min, Non-bias

Duration: 500 cycles

2. DRAM Products

Package Type	Period	Total No of Samples	No. of Fails	Reject Information
TSOP	Q2,11	77	0	
	Q3,11	-	-	
	Q4,11	-	-	
BGA	Q2,11	77	0	
	Q3,11	77	0	
	Q4,11	77	0	

3. Non-Volatile Memory Products

Package Type	Period	Total No of Samples	No. of Fails	Reject Information
SOP	Q2,11	77	0	
	Q3,11	77	0	
	Q4,11	77	0	

Pressure Cooker Test (PCT)

1. Test Condition

Condition: T = 121°C, RH = 100%, Non-bias

Duration: 168 hrs

2. DRAM Products

Package Type	Period	Total No of Samples	No. of Fails	Reject Information
BGA	Q2,11	77	0	
	Q3,11	77	0	
	Q4,11	77	0	

3. Non-Volatile Memory Products

Package Type	Period	Total No of Samples	No. of Fails	Reject Information
SOP	Q2,11	77	0	
	Q3,11	77	0	
	Q4,11	77	0	

Highly Accelerated Stress Test (HAST)

1. Test Condition

Condition: T = 130°C for TSOP/SOP

T = 121°C for BGA

RH = 85%.

Duration: 168 hrs

2. DRAM Products

Package Type	Period	Total No of Samples	No. of Fails	Reject Information
TSOP	Q2,11	77	0	
	Q3,11	-	-	
	Q4,11	-	-	
BGA	Q2,11	102	0	
	Q3,11	77	0	
	Q4,11	77	0	

3. Non-Volatile Memory Products

Package Type	Period	Total No of Samples	No. of Fails	Reject Information
SOP	Q2,11	77	0	
	Q3,11	77	0	
	Q4,11	77	0	